

672-Pin FineLine Ball-Grid Array (FBGA), Option 1 — Flip Chip

- All dimensions and tolerances conform to ASME Y14.5M - 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	Specification
Ordering Code Reference	F
Package Acronym	FBGA
Substrate Material	BT
Solder Ball Composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MS-034 Variation: AAL-1
Lead Coplanarity	0.008 inches (0.20 mm)
Weight	10.2 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	—	—	3.50
A1	0.30	—	—
A2	0.25	—	3.00
A3	—	—	2.50
D	27.00 BSC		
E	27.00 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		

Package Outline

